

SIGNATURE SERIES Comparators

LM393xxx LM2903xx LM339xx LM2901xx

General Description

LM393xxx, LM2903xx, LM339xx, and LM2901xx monolithic ICs integrate two or four independent comparator circuits on a single chip and feature high gain, low power consumption, and an operating voltage range from 2V to 36V (single power supply).

Features

- Operable with a Single Power Supply
- Wide Operating Supply Voltage Range

LM393DT

LM393PT

1 M393WPT

LM2903PT

LM393ST

LM393WDT LM2903DT

- Input / Output Ground Sense
- Low Supply Current
- Open Collector
- Wide Temperature Range

Application

- Consumer Electronics
- Current Sense Application
- Battery Monitor
- Multivibrator

Pin Configuration

(SOP-J8)

TSSOP8: (TSSOP-B8)

Mini SO8:

(TSSOP-B8J)

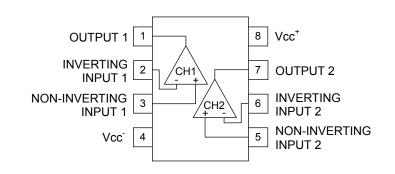
SO Package8:

Key Specifications

Operating Supply Volta	ge:
Single Supply	+2V to +36V
Dual Supply	±1V to ±18V
Supply Current:	
LM393xxx/LM2903xx	0.4mA (Typ)
LM339xx/LM2901xx	1.1mA (Typ)
Input Bias Current:	25nA (Typ)
Input Offset Current:	5nA (Typ)
Temperature Range:	
LM393xx/LM339xxx	-40°C to + 85°C
LM2903xx/LM2901xx	-40°C to +125°C
Packages	W(Typ) x D(Typ) x H(Max)

Packages

SO Package8	4.90mm x 6.0mm x 1.55mm
TSSOP8	3.00mm x 6.4mm x 1.10mm
Mini SO8	3.00mm x 4.9mm x 0.95mm
SO Package14	8.65mm x 6.0mm x 1.55mm
TSSOP14	5.00mm x 6.4mm x 1.10mm



Pin Description

LM393xxx/LM2903xx

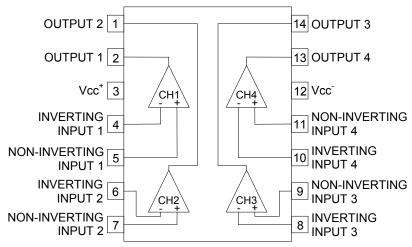
Pin No.	Pin Name	Function
1	OUTPUT 1	CH1 Output
2	INVERTING INPUT 1	CH1 Inverting Input
3	NON-INVERTING INPUT 1	CH1 Non-inverting Input
4	Vcc ⁻	Negative power supply
5	NON-INVERTING INPUT 2	CH2 Non-inverting Input
6	INVERTING INPUT 2	CH2 Inverting Input
7	OUTPUT 2	CH2 Output
8	Vcc⁺	Positive power supply

OProduct structure : Silicon monolithic integrated circuit OThis product is not designed protection against radioactive rays.

Pin Configuration

SO Package14:	LM339DT
(SOP-J14)	LM2901DT
TSSOP14:	LM339PT

(TSSOP-B14J) LM2901PT



Pin Description

LM339xx/LM2	90188	
Pin No.	Pin Name	Function
1	OUTPUT 2	CH2 Output
2	OUTPUT 1	CH1 Output
3	Vcc⁺	Positive power supply
4	INVERTING INPUT 1	CH1 Inverting Input
5	NON-INVERTING INPUT 1	CH1 Non-inverting Input
6	INVERTING INPUT 2	CH2 Inverting Input
7	NON-INVERTING INPUT 2	CH2 Non-inverting Input
8	INVERTING INPUT 3	CH3 Inverting Input
9	NON-INVERTING INPUT 3	CH3 Non-inverting Input
10	INVERTING INPUT 4	CH4 Inverting Input
11	NON-INVERTING INPUT 4	CH4 Non-inverting Input
12	Vcc ⁻	Negative power supply
13	OUTPUT 4	CH4 Output
14	OUTPUT 3	CH3 Output

Circuit Diagram

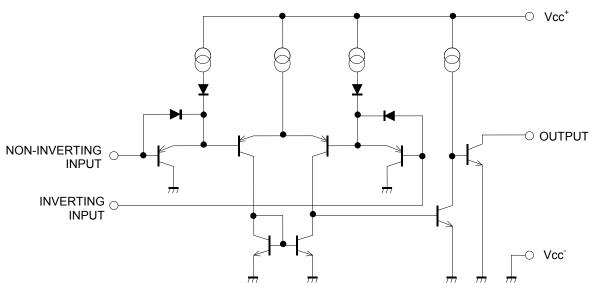


Figure 1. Circuit Diagram (each channel)

Absolute Maximum Ratings (T_A=25°C)

Deremeter		Symbol		Ratings					
Parameter	Symbol		LM393xxx	LM339xx	LM2903xx	LM2901xx	Unit		
Supply Voltage		Vcc ⁺ -Vcc ⁻		+:	36		V		
		SO Package8	0.67 ^(Note 1,6)	-	0.67 ^(Note 1,6)	-			
		TSSOP8	0.62 ^(Note 2,6)	-	0.62 ^(Note 2,6)	-			
Power Dissipation	PD	Mini SO8	0.58 ^(Note 3,6)	-	-	-	W		
		SO Package14	-	1.02 ^(Note 4,6)	-	1.02 ^(Note 4,6)			
		TSSOP14	-	0.84 ^(Note 5,6)	-	0.84 ^(Note 5,6)			
Differential Input Voltage ^(Note 7)		V _{ID}		V					
Input Common-mode Voltage Range		VICM			V				
Input Current ^(Note 8)		h		-10					
Operating Supply Voltage		Vopr			o +36.0 o ±18.0)		V		
Operating Temperature Range	Topr		-40 to +85 -40 to +125				°C		
Storage Temperature Range	Tstg			°C					
Maximum Junction Temperature		Tjmax		+150					

Note: Absolute maximum rating item indicates the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

To use at temperature above T_A=25°C reduce 5.4mW. To use at temperature above T_A=25°C reduce 5.0mW. (Note 1)

(Note 2)

To use at temperature above $T_A=25^{\circ}C$ reduce 0.0mW. To use at temperature above $T_A=25^{\circ}C$ reduce 4.7mW. To use at temperature above $T_A=25^{\circ}C$ reduce 8.2mW. (Note 3) (Note 4)

To use at temperature above TA=25°C reduce 6.8mW. (Note 5)

(Note 6)

Mounted on a FR4 glass epoxy PCB 70mm×70mm×1.6mm(Copper foil area less than 3%).

The voltage difference between inverting input and non-inverting input is the differential input voltage. (Note 7)

The input terminal voltage is set to more than Vcc⁻. (Note 8)

An excessive input current will flow when input voltages of less than Vcc⁻-0.6V are applied.

The input current can be set to less than the rated current by adding a limiting resistor. **Caution:** Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Electric Characteristics

OLM393xxx(Unless otherwise specified Vcc⁺=+5V, Vcc⁻=0V, $T_A=25^{\circ}C$)

Parameter	Currence al	Temperature	Limit			Unit	Conditions	
Falameter	Symbol	Range	Min	Тур	Max	Onit	Conditions	
Input Offset Voltage (Note 9,10)	V _{IO}	25°C	-	1	7	mV	$Vcc^+=5V$ to 30V, $V_0=1.4V$	
input Onset voltage	VIO	Full range	-	-	9	IIIV	V _{ICM} =0 to 1.5V	
Input Offset Current (Note 9,10)	l	25°C	-	5	50	nA	V ₀ =1.4V	
input Onset Current	I _{IO}	Full range	-	-	150	ПА	V ₀ -1.4V	
Input Bias Current (Note 9,10)	L.	25°C	-	25	250	nA	V ₀ =1.4V	
input bias Current (I _{IB}	Full range	-	-	400	ΠA	v ₀ -1.4v	
Large Signal Voltage Gain	Av	25°C	25	200	-	V/mV	$Vcc^{+}=15V$ V ₀ =1.4V to 11.4V, R _L =15kΩ	
Supply Current (Note 10)	I _{CC}	25°C	-	0.4	1	mA	Vcc ⁺ =5V, No Load	
(All Comparators)		Full range	-	1	2.5		Vcc ⁺ =30V, No Load	
Input Common-mode	V _{ICM}	25°C	0	-	Vcc ⁺ -1.5	V	_	
Voltage Range (Note 10)		Full range	0	-	Vcc ⁺ -2.0	v	-	
Output Saturation Voltage (Note 10)	Max	25°C	-	250	400	mV	VID=-1V. ISINK=4mA	
(Low Level Output Voltage)	V _{OL}	Full range	-	-	700	IIIV	VIDIV, ISINK-411A	
Output Leakage Current (Note 10)	L	25°C	-	0.1	-	nA	Vcc ⁺ =30V, V _{ID} =1V	
(High Level Output Current)	I _{LEAK}	Full range	-	I	1	μA	V _O =30V	
Output Sink Current (Note 10,11)	I _{SINK}	Full range	6	16	-	mA	V _{ID} =-1V, V _O =1.5V	
Small Signal Response Time	t _{RE}	25°C	-	1.3	-	μs	R_L =5.1k Ω , V_{RL} =5V V_{IN} =100mVp-p, Overdrive=5mV	
Large Signal Response Time	t _{REL}	25°C	-	300	-	ns	R _L =5.1kΩ, V _{RL} =5V V _{IN} =TTL input, V _{REF} =1.4V	

(Note 9) Absolute value
 (Note 10) Full range: T_A=-40°C to +85°C
 (Note 11) Consider the power dissipation of the IC under high temperature environment when selecting the output current value. There may be a case where the output current value is reduced due to the rise in IC temperature caused by the heat generated inside the IC.

Electric Characteristics - continued

OLM339xx(Unless otherwise specified Vcc⁺=+5V, Vcc⁻=0V, T_A=25°C)

Parameter	Symbol	Temperature		Limit			Conditions	
Falameter	Symbol	Range	Min	Тур	Max	Unit	Conditions	
Input Offset Voltage (Note 12,13)	V _{IO}	25°C	-	1	7	mV	$Vcc^{+}=5V$ to 30V, $V_{O}=1.4V$	
input Onset voltage	V IO	Full range	-	-	9	IIIV	V _{ICM} =0 to 1.5V	
Input Offset Current (Note 12,13)	l.a.	25°C	-	5	50	nA	V ₀ =1.4V	
input Onset Current	I _{IO}	Full range	-	-	150	ПА	V ₀ -1.4V	
Input Bias Current (Note 12,13)	I _{IB}	25°C	-	25	250	nA	V ₀ =1.4V	
input bias Current	ιB	Full range	-	-	400	ПА	V0-1.4V	
Large Signal Voltage Gain	Av	25°C	25	200	-	V/mV	Vcc ⁺ =15V V ₀ =1.4V to 11.4V, R _L =15kΩ	
Supply Current (Note 13)	I _{CC}	25°C	-	1.1	2	mA	Vcc ⁺ =5V, No Load	
(All Comparators)		Full range	-	1.3	2.5	ШA	Vcc ⁺ =30V, No Load	
Input Common-mode	VICM	25°C	0	-	Vcc ⁺ -1.5	V	-	
Voltage Range (Note 13)		Full range	0	-	Vcc ⁺ -2.0	V		
Output Saturation Voltage (Note 13)	V	25°C	-	250	400	mV	V _{ID} =-1V, I _{SINK} =4mA	
(Low Level Output Voltage)	V _{OL}	Full range	-	-	700	IIIV		
Output Leakage Current (Note 13)	1	25°C	-	0.1	-	nA	Vcc ⁺ =30V, V _{ID} =1V	
(High Level Output Current)	I _{LEAK}	Full range	-	I	1	μA	V ₀ =30V	
Output Sink Current (Note 13,14)	I _{SINK}	Full range	6	16	-	mA	V _{ID} =-1V, V _O =1.5V	
Small Signal Response Time	t _{RE}	25°C	-	1.3	-	μs	$\begin{array}{l} R_L = 5.1 k \Omega, \ V_{RL} = 5 V \\ V_{IN} = 100 m V p - p, \\ Overdrive = 5 m V \end{array}$	
Large Signal Response Time	t _{REL}	25°C	-	300	-	ns	R_L =5.1k Ω , V_{RL} =5V V_{IN} =TTL input, V_{REF} =1.4V	

(Note 12) Absolute value (Note 13) Full range: T_A=-40°C to +85°C (Note 14) Consider the power dissipation of the IC under high temperature environment when selecting the output current value. There may be a case where the output current value is reduced due to the rise in IC temperature caused by the heat generated inside the IC.

Electric Characteristics - continued

OLM2903xx(Unless otherwise specified Vcc⁺=+5V, Vcc⁻=0V, $T_A=25^{\circ}C$)

Parameter	Symbol	Temperature		Limit		Unit	Conditions	
Falameter	Symbol	Range	Min	Тур	Max	Onit	Conditions	
Input Offset Voltage (Note 15,16)	V	25°C	-	2	7	mV	$Vcc^{+}=5V$ to 30V, $V_{O}=1.4V$	
input Onset voltage (and the)	V _{IO}	Full range	-	-	15	mv	V _{ICM} =0 to 1.5V	
Input Offset Current (Note 15,16)	1	25°C	-	5	50	nA	V ₀ =1.4V	
Input Onset Current	I _{IO}	Full range	-	-	150	ΠA	v ₀ -1.4v	
Input Bias Current (Note 15,16)	I	25°C	-	25	250	nA	V ₀ =1.4V	
input bias Current	I _{IB}	Full range	-	-	400	ПА	V ₀ -1.4V	
Large Signal Voltage Gain	Av	25°C	25	200	-	V/mV	Vcc ⁺ =15V V ₀ =1.4V to 11.4V, R _L =15kΩ	
Supply Current (Note 16)	I _{CC}	25°C	-	0.4	1	mA	Vcc ⁺ =5V, No Load	
(All Comparators)		Full range	-	1	2.5		Vcc ⁺ =30V, No Load	
Input Common-mode	VICM	25°C	0	-	Vcc ⁺ -1.5	V		
Voltage Range (Note 16)		Full range	0	-	Vcc ⁺ -2.0	v	-	
Output Saturation Voltage (Note 16)	V _{OL}	25°C	-	250	400	mV	V _{ID} =-1V, I _{SINK} =4mA	
(Low Level Output Voltage)		Full range	-	-	700	IIIV	VIDIV, ISINK-4IIIA	
Output Leakage Current (Note 16)		25°C	-	0.1	-	nA	Vcc⁺=30V, V _{ID} =1V	
(High Level Output Current)	ILEAK	Full range	-	-	1	μA	V ₀ =30V	
Output Sink Current (Note 16,17)	I _{SINK}	Full range	6	16	-	mA	V _{ID} =-1V, V _O =1.5V	
Small Signal Response Time	t _{RE}	25°C	-	1.3	-	μs	R_L =5.1k Ω , V_{RL} =5V V_{IN} =100mVp-p, Overdrive=5mV	
Large Signal Response Time	t _{REL}	25°C	-	-	1.0	μs	$\begin{array}{l} R_L = 5.1 k\Omega, \ V_{RL} = 5 V \\ V_{IN} = TTL \ input, \ V_{REF} = 1.4 V \\ V_O \ at \ 95\% \end{array}$	

(Note 15) Absolute value (Note 16) Full range: T_A=-40°C to +125°C (Note 17) Consider the power dissipation of the IC under high temperature environment when selecting the output current value. There may be a case where the output current value is reduced due to the rise in IC temperature caused by the heat generated inside the IC.

Electric Characteristics - continued

OLM2901xx(Unless otherwise specified Vcc⁺=+5V, Vcc⁻=0V, $T_A=25^{\circ}C$)

Parameter	Symbol	Temperature	Limit			Unit	Conditions	
Parameter	Symbol	Range	Min	Тур	Max	Unit	Conditions	
Input Offset Voltage (Note 15,16)	V _{IO}	25°C	-	1	7	mV	$Vcc^{+}=5V$ to 30V, $V_{O}=1.4V$	
Input Onset Voltage	V IO	Full range	-	-	15	IIIV	V _{ICM} =0 to 1.5V	
Input Offset Current (Note 15,16)	I _{IO}	25°C	-	5	50	nA	V ₀ =1.4V	
input Onset Gunent	ιO	Full range	-	-	150		V0-1.4V	
Input Bias Current (Note 15,16)	I _{IB}	25°C	_	25	250	nA	V ₀ =1.4V	
	ιB	Full range	-	-	400			
Large Signal Voltage Gain	Av	25°C	25	200	-	V/mV	Vcc ⁺ =15V V ₀ =1.4V to 11.4V, R _L =15kΩ	
Supply Current (Note 16)	I _{CC}	25°C	-	1.1	2	mA	Vcc ⁺ =5V, No Load	
(All Comparators)		Full range	-	1.3	2.5		Vcc ⁺ =30V, No Load	
Input Common-mode	VICM	25°C	0	-	Vcc ⁺ -1.5	V	_	
Voltage Range (Note 16)		Full range	0	-	Vcc ⁺ -2.0	v	-	
Output Saturation Voltage (Note 16)	V _{OL}	25°C	-	250	400	mV	V _{ID} =-1V, I _{SINK} =4mA	
(Low Level Output Voltage)		Full range	-	-	700	IIIV		
Output Leakage Current (Note 16)	l	25°C	-	0.1	-	nA	Vcc ⁺ =30V, V _{ID} =1V	
(High Level Output Current)	I _{LEAK}	Full range	-	-	1	μA	V _O =30V	
Output Sink Current (Note 16,17)	I _{SINK}	Full range	6	16	-	mA	V _{ID} =-1V, V _O =1.5V	
Small Signal Response Time	t _{RE}	25°C	-	1.3	-	μs	$\begin{array}{l} R_L = 5.1 k\Omega, \ V_{RL} = 5 V \\ V_{IN} = 100 mV p - p, \\ Overdrive = 5 mV \end{array}$	
Large Signal Response Time	t _{REL}	25°C	-	-	1.0	μs	$\begin{array}{l} R_L = 5.1 k\Omega, \ V_{RL} = 5 V \\ V_{IN} = TTL \ input, \ V_{REF} = 1.4 V \\ V_O \ at \ 95\% \end{array}$	

(Note 18) Absolute value (Note 19) Full range: T_A=-40°C to +125°C (Note 20) Consider the power dissipation of the IC under high temperature environment when selecting the output current value. There may be a case where the output current value is reduced due to the rise in IC temperature caused by the heat generated inside the IC.

Description of Electrical Characteristics

Described below are descriptions of the relevant electrical terms used in this datasheet. Items and symbols used are also shown. Note that item name and symbol and their meaning may differ from those on another manufacturer's document or general document.

1. Absolute maximum ratings

Absolute maximum rating items indicate the condition which must not be exceeded. Application of voltage in excess of absolute maximum rating or use out of absolute maximum rated temperature environment may cause deterioration of characteristics.

- (1) Supply Voltage (Vcc⁺/ Vcc⁻) Indicates the maximum voltage that can be applied between the positive power supply pin and negative power supply pin without deterioration or destruction of characteristics of internal circuit.
- (2) Differential Input Voltage (V_{ID}) Indicates the maximum voltage that can be applied between non-inverting and inverting pins without damaging the IC.
- (3) Input Common-mode Voltage Range (V_{ICM}) Indicates the maximum voltage that can be applied to the non-inverting and inverting pins without deterioration or destruction of electrical characteristics. Input common-mode voltage range of the maximum ratings does not assure normal operation of IC. For normal operation, use the IC within the input common-mode voltage range characteristics.
- (4) Operating and storage temperature ranges (Topr, Tstg) The operating temperature range indicates the temperature range within which the IC can operate. The higher the ambient temperature, the lower the power consumption of the IC. The storage temperature range denotes the range of temperatures the IC can be stored under without causing excessive deterioration of the electrical characteristics.
- (5) Power dissipation (PD) Indicates the power that can be consumed by the IC when mounted on a specific board at ambient temperature 25°C(normal temperature). As for package product, PD is determined by the temperature that can be permitted by the IC in the package (maximum junction temperature) and the thermal resistance of the package.

2. Electrical characteristics

- (1) Input Offset Voltage (V_{IO}) Indicates the voltage difference between non-inverting pin and inverting pins. It can be translated into the input voltage difference required for setting the output voltage at 0 V.
- Input Offset Current (I_{IO})
 Indicates the difference of input bias current between the non-inverting and inverting pins.
- (3) Input Bias Current (I_B) Indicates the current that flows into or out of the input pin. It is defined by the average of input bias currents at the non-inverting and inverting pins.
- (4) Large Signal Voltage Gain (A_V)
 Indicates the amplifying rate (gain) of output voltage against the voltage difference between non-inverting pin and inverting pin. It is normally the amplifying rate (gain) with reference to DC voltage.
 A_V = (Output Voltage) / (Differential Input Voltage)
- (5) Supply Current (I_{CC}) Indicates the current that flows within the IC under specified no-load conditions.
- (6) Input Common-mode Voltage Range (V_{ICM})
 Indicates the input voltage range where IC normally operates.
- (7) Output Saturation Voltage, Low Level Output Voltage (V_{OL}) Signifies the voltage range that can be output under specific output conditions.
- (8) Output Leakage Current, High Level Output Current (I_{LEAK}) Indicates the current that flows into the IC under specific input and output conditions.
- (9) Output Sink Current (I_{SINK}) Denotes the maximum current that can be output from the IC under specific output conditions.
- (10) Response Time (t_{RE}) Response time indicates the delay time between the input and output signal which is determined by the time difference from the fifty percent of input signal swing to the fifty percent of output signal swing.

Typical Performance Curves

OLM393xxx/LM2903xx

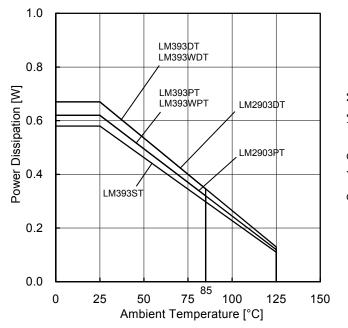
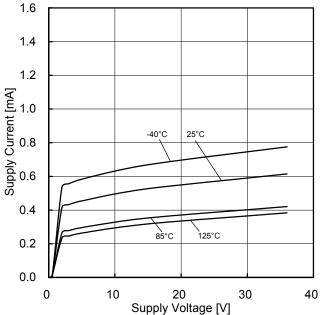


Figure 2. Power Dissipation vs Ambient Temperature (Derating Curve)





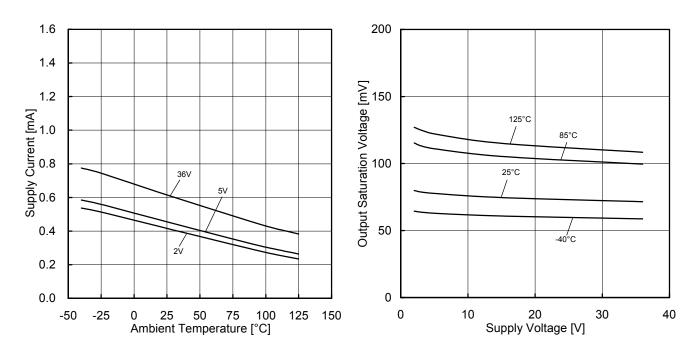
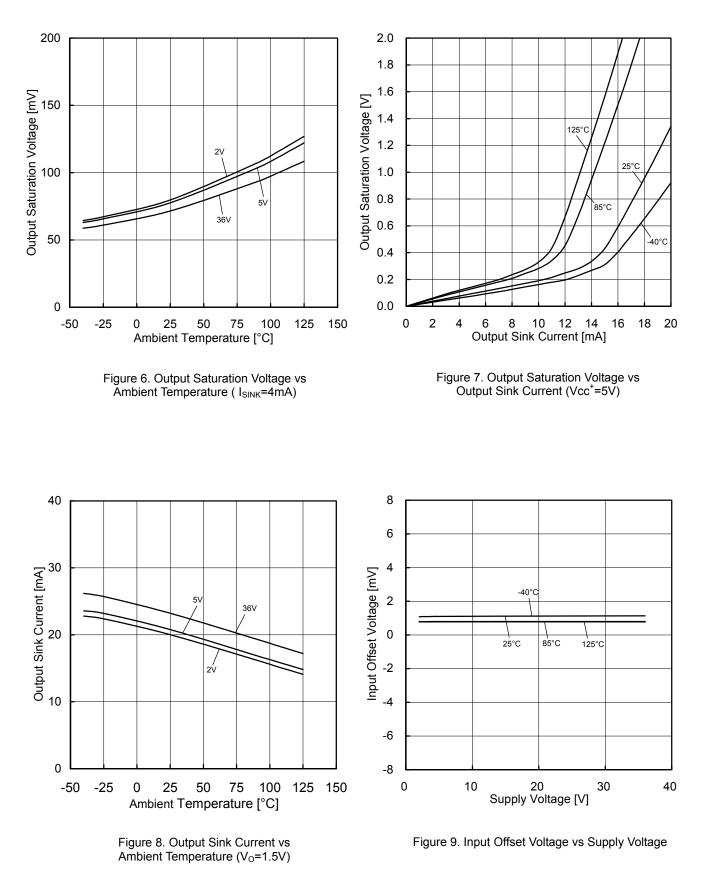


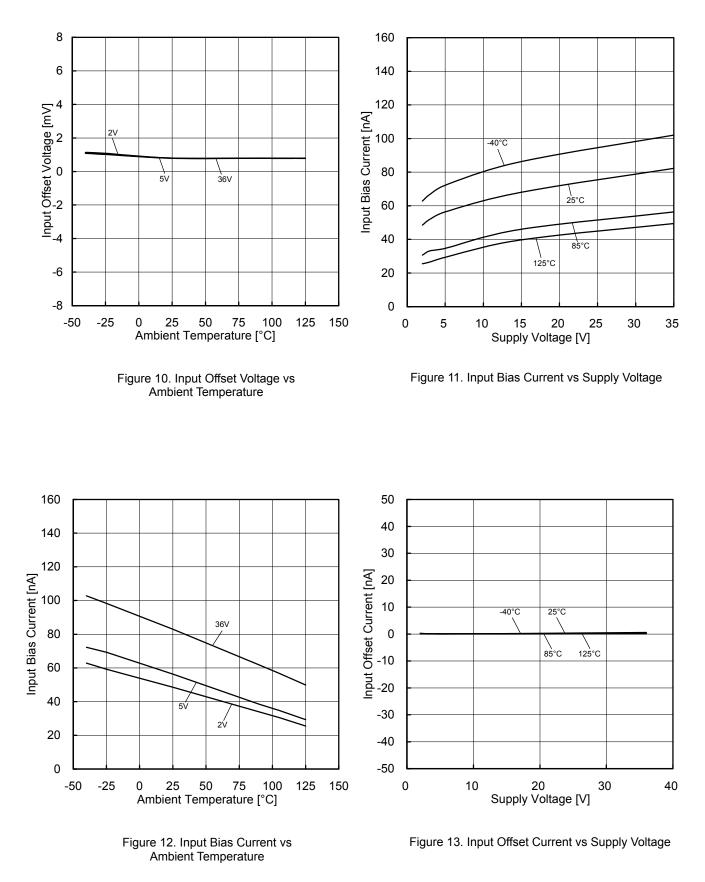
Figure 4. Supply Current vs Ambient Temperature

Figure 5. Output Saturation Voltage vs Supply Voltage $(I_{SINK}=4mA)$

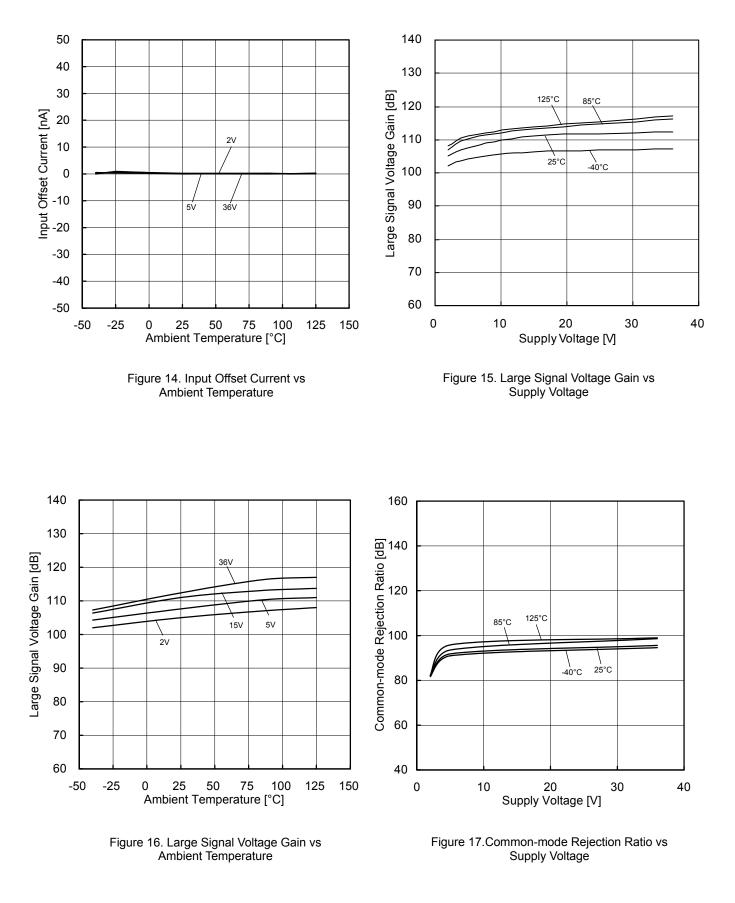
OLM393xxx/LM2903xx



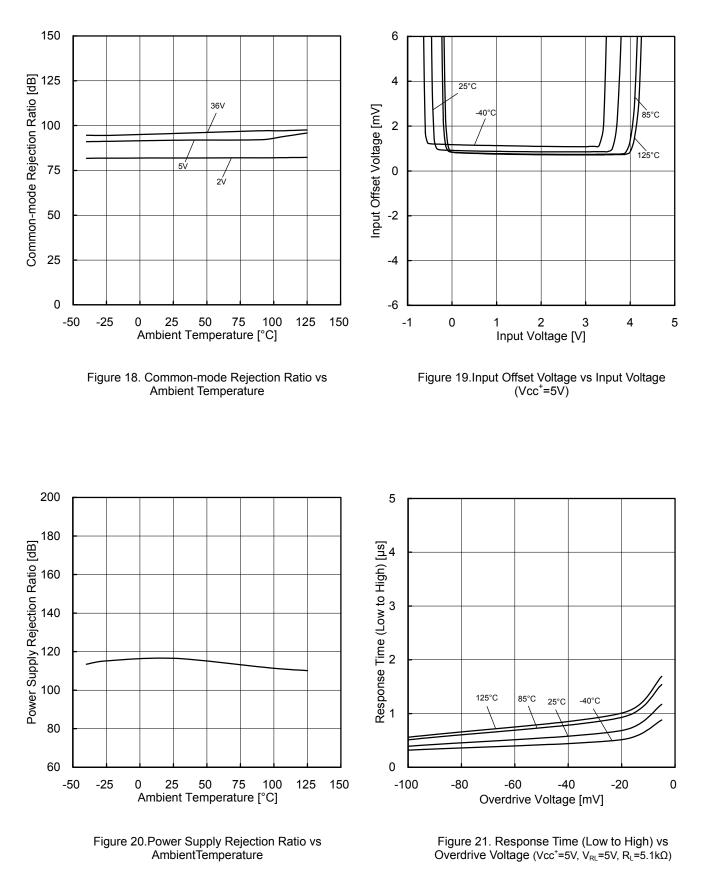
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OLM393xxx/LM2903xx

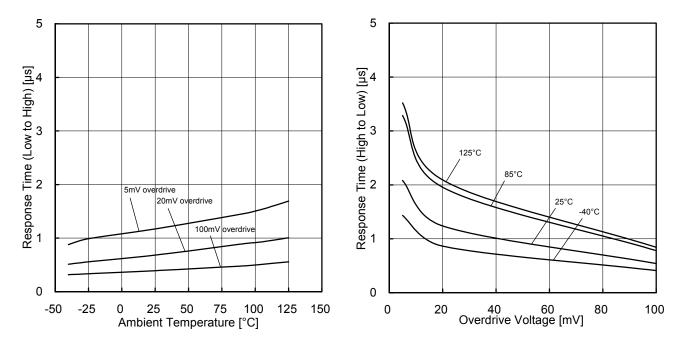


Figure 22. Response Time (Low to High) vs Ambient Temperature (Vcc⁺=5V, V_{RL}=5V, R_L=5.1kΩ)

Figure 23. Response Time (High to Low) vs Overdrive Voltage (Vcc⁺=5V, V_{RL}=5V, R_L=5.1k Ω)

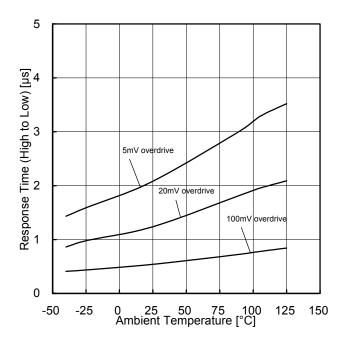


Figure 24. Response Time (High to Low) vs Ambient Temperature (Vcc⁺=5V, V_{RL}=5V, R_L=5.1k Ω)

OLM339xx/LM2901xx

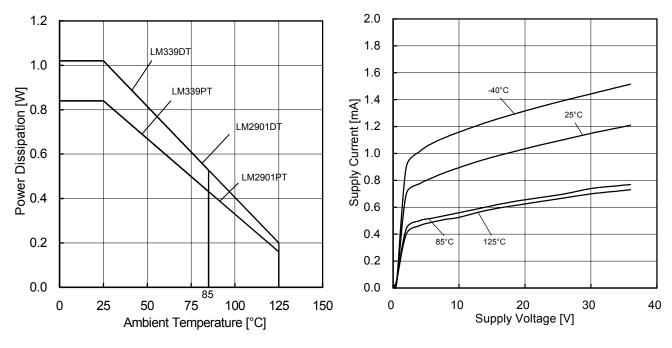


Figure 25. Power Dissipation vs Ambient Temperature (Derating Curve)

Figure 26.Supply Current vs Supply Voltage

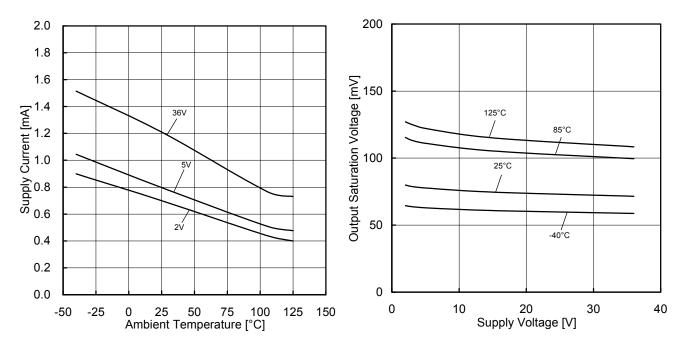
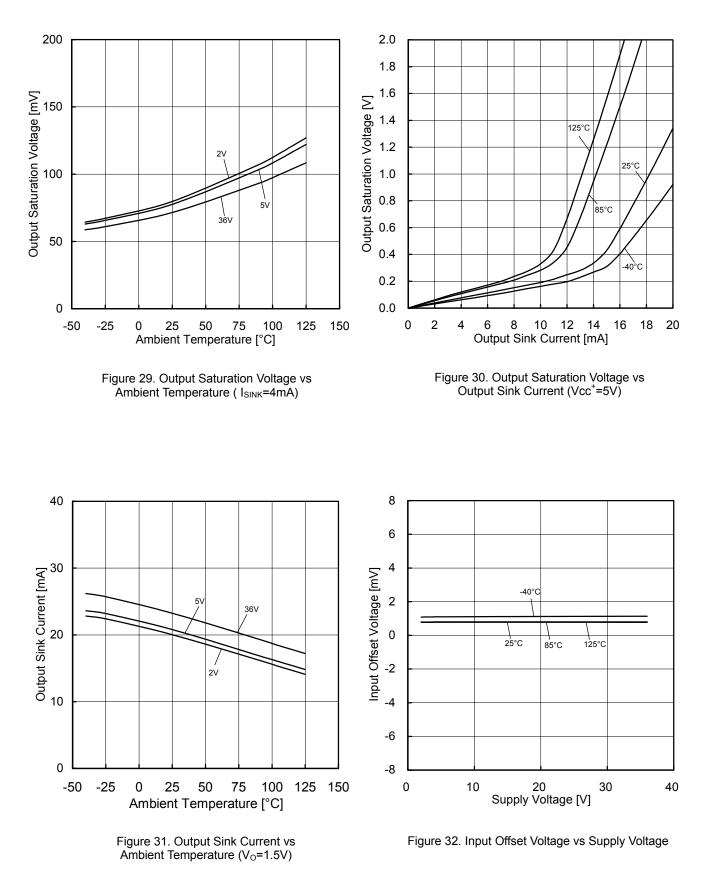


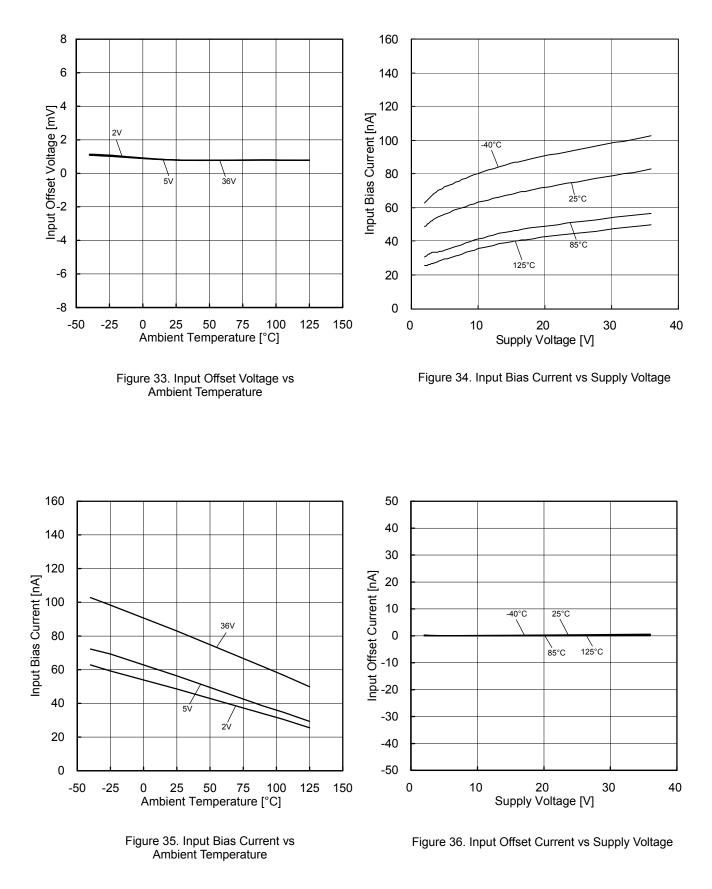
Figure 27. Supply Current vs Ambient Temperature

Figure 28. Output Saturation Voltage vs Supply Voltage (I_{SINK}=4mA)

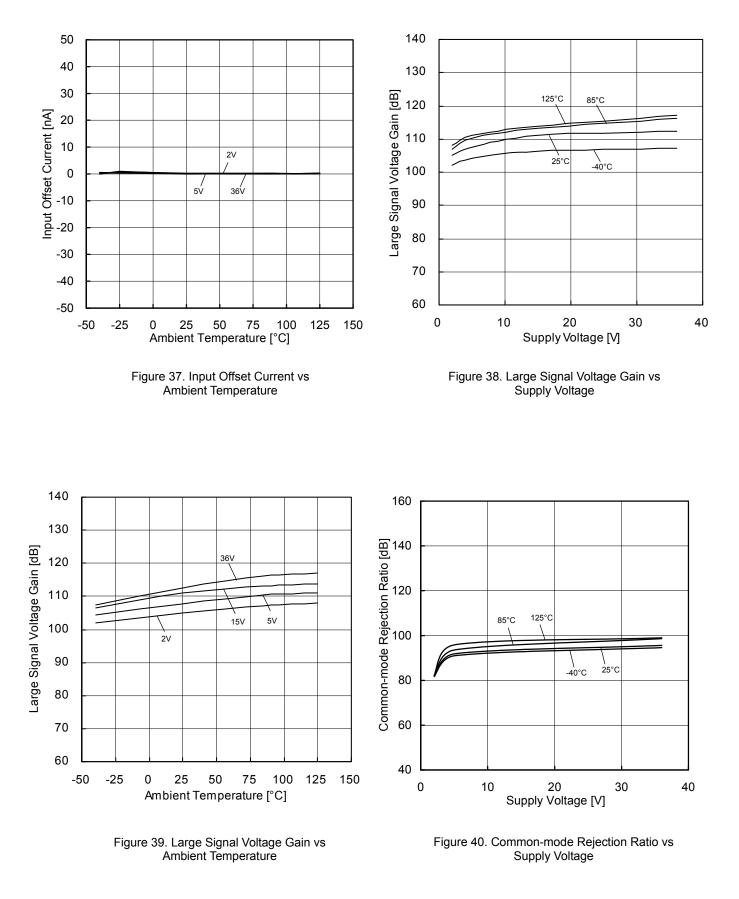
OLM339xx/LM2901xx



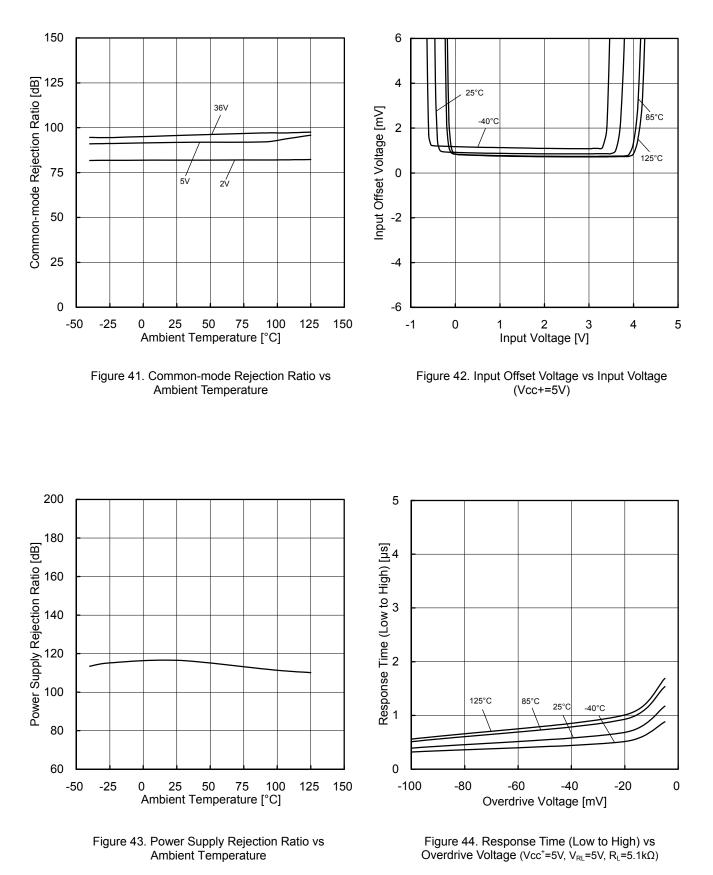
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OLM339xx/LM2901xx

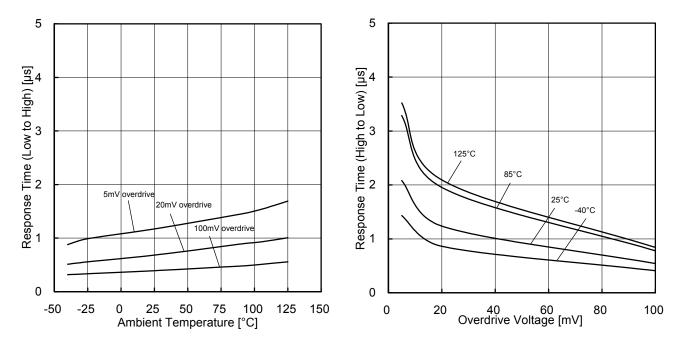
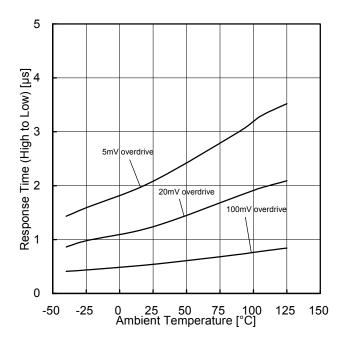
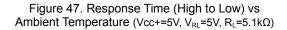


Figure 45. Response Time (Low to High) vs Ambient Temperature (Vcc^{+} =5V, V_{RL} =5V, R_{L} =5.1k Ω)

Figure 46. Response Time (High to Low) vs Overdrive Voltage (Vcc⁺=5V, V_{RL}=5V, R_L=5.1k Ω)





Application Information

Measurement Circuit 1 NULL Method Measurement Condition

							٧	/cc⁺,Vcc⁻,	E_{K} , V_{ICM} unit : V
Parameter	VF	SW1	SW2	SW3	Vcc⁺	Vcc	Eκ	VICM	Calculation
Input Offset Voltage	VF1	ON	ON	ON	5 to 30	0	-1.4	0	1
Input Offset Current	VF2	OFF	OFF	ON	5	0	-1.4	0	2
Input Rice Current	VF3	OFF	ON	ON	5	0	-1.4	0	3
Input Bias Current	VF4	ON	OFF	ON	5	0	-1.4	0	3
	VF5				15	0	-1.4	0	4
Large Signal Voltage Gain	VF6	ON	ON	ON	15	0	-11.4	0	4

-Calculation-

1. Input Offset Voltage (VIO)

$$V_{IO} = \frac{|V_{F1}|}{1 + R_{F}/R_{s}}$$
 [V]

2. Input Offset Current (I_{IO}) $I_{IO} = -$

$$_{\rm IO} = \frac{|V_{\rm F2}-V_{\rm F1}|}{R_{\rm I} \times (1+R_{\rm F}/R_{\rm S})} \quad [A]$$

 $\left|V_{F4}\text{-}V_{F3}\right|$

 $2 \times R_I \times (1 + R_F/R_S)$

[A]

I_B =

3. Input Bias Current (I_B)

4. Large Signal Voltage Gain (A_V)

$$A_V = 20Log \quad \frac{10 \times (1 + R_F/R_S)}{|V_{F5} - V_{F6}|} \quad [dB]$$

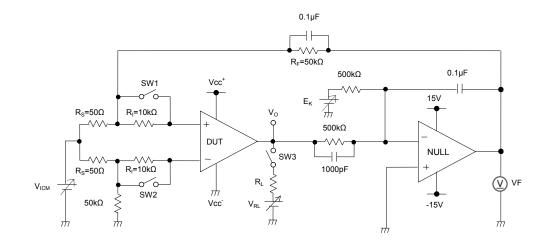


Figure 48. Measurement Circuit 1 (each Comparator)

Application Information - continued Measurement Circuit 2: Switch Condition

Measurement Oncult 2. 5V								
SW No.		SW1	SW2	SW3	SW4	SW5	SW6	SW7
Supply Current	-	ON	OFF	ON	OFF	OFF	OFF	OFF
Output Sink Current	V ₀ =1.5V	ON	OFF	ON	OFF	ON	ON	OFF
Output Saturation Voltage	I _{SINK} =4mA	ON	OFF	ON	OFF	OFF	OFF	ON
Output Leakage Current	V ₀ =36V	ON	OFF	ON	OFF	OFF	OFF	ON
Response Time	$R_L=5.1k\Omega$	ON		OFF	ON	OFF	ON	OFF
	V _{RL} =5V	UN	ON	UFF	UN			OFF

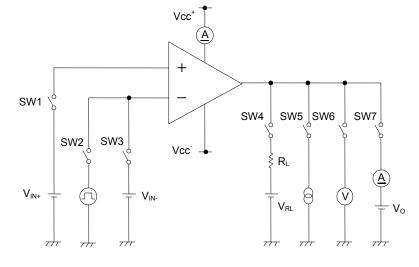
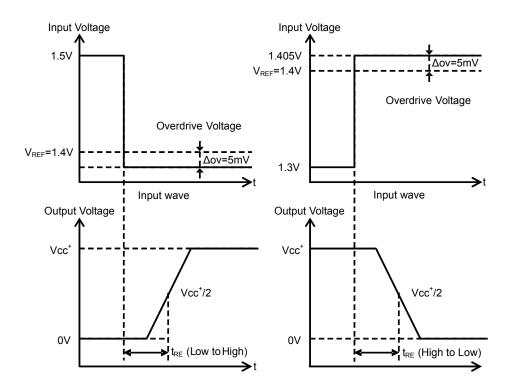


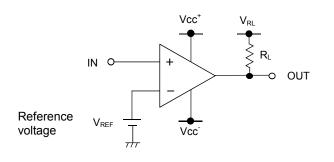
Figure 49. Measurement Circuit 2 (each Comparator)

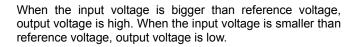


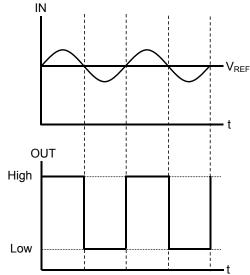


Example of Circuit

OReference voltage is VIN-

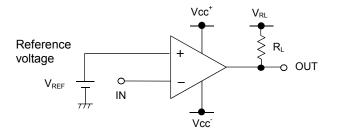






IN VREF OUT High Low

OReference voltage is VIN+



When the input voltage is smaller than reference voltage, output voltage is high. When the input voltage is bigger than reference voltage, output voltage is low.

Power Dissipation

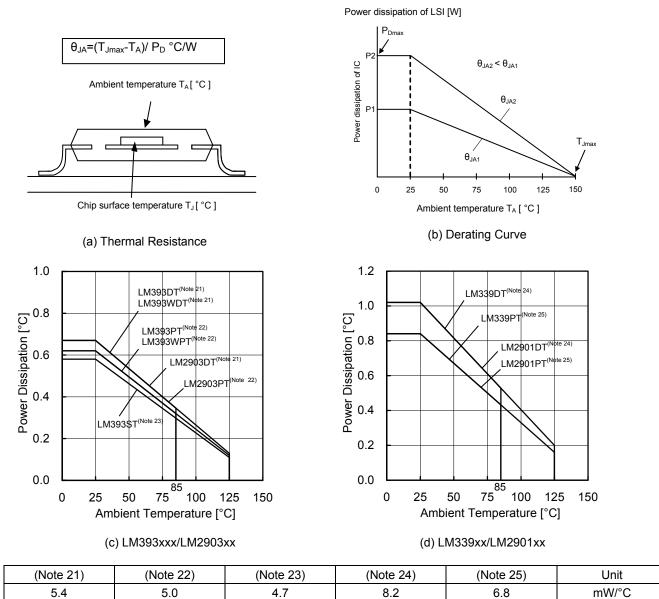
Power dissipation (total loss) indicates the power that the IC can consume at $T_A=25$ °C (normal temperature). As the IC consumes power, it heats up, causing its temperature to be higher than the ambient temperature. The allowable temperature that the IC can accept is limited. This depends on the circuit configuration, manufacturing process, and consumable power.

Power dissipation is determined by the allowable temperature within the IC (maximum junction temperature) and the thermal resistance of the package used (heat dissipation capability). Maximum junction temperature is typically equal to the maximum storage temperature. The heat generated through the consumption of power by the IC radiates from the mold resin or lead frame of the package. Thermal resistance, represented by the symbol θ_{JA} °C/W, indicates this heat dissipation capability. Similarly, the temperature of an IC inside its package can be estimated by thermal resistance.

Figure 51(a) shows the model of the thermal resistance of a package. The equation below shows how to compute for the Thermal resistance (θ_{JA}), given the ambient temperature (T_A), maximum junction temperature (T_{Jmax}), and power dissipation (P_D).

$$\theta_{JA} = (T_{Jmax} - T_A) / PD$$
 °C/W

The Derating curve in Figure 51(b) indicates the power that the IC can consume with reference to ambient temperature. Power consumption of the IC begins to attenuate at certain temperatures. This gradient is determined by Thermal resistance (θ_{JA}), which depends on the chip size, power consumption, package, ambient temperature, package condition, wind velocity, etc. This may also vary even when the same package is used. Thermal reduction curve indicates a reference value measured at a specified condition. Figure 51(c) and (d) shows an example of the derating curve for LM393xxx, LM2903xx, LM339xx, and LM2901xx.



When using the unit above $T_A=25^{\circ}$ C, subtract the value above per Celsius degree.

Power dissipation is the value when FR4 glass epoxy board 70mm ×10mm ×1.6mm (cooper foil area below 3%) is mounted.

Figure 51. Thermal Resistance and Derating Curve

Operational Notes

1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

2. Power Supply Lines

Design the PCB layout pattern to provide low impedance ground and supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The power supply and ground lines must be as short and thick as possible to reduce line impedance.

5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded, the rise in temperature of the chip may result in deterioration of the properties of the chip. The absolute maximum rating of the PD stated in this specification is when the IC is mounted on a 70mm x 70mm x 1.6mm glass epoxy board. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the PD rating.

6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

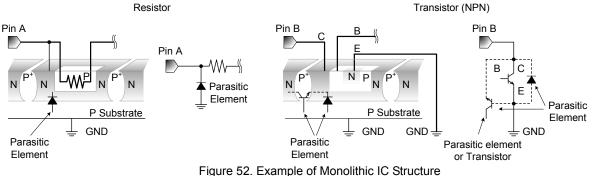
Operational Notes – continued

11. Regarding Input Pins of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.



12. Unused Circuits

When there are unused circuits it is recommended that they be connected as in Figure 53, setting the non-inverting input pin to a potential within the in-phase input voltage range (V_{ICM}).

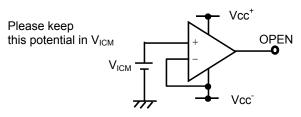


Figure 53. Disable Circuit Example

13. Input Voltage

Applying Vcc⁻ + 36V to the input pin is possible without causing deterioration of the electrical characteristics or destruction, regardless of the supply voltage. However, this does not ensure normal circuit operation. Please note that the circuit operates normally only when the input voltage is within the common-mode input voltage range of the electric characteristics.

14. Power Supply (single/dual)

The comparator operates when the specified voltage supplied is between Vcc⁺ and Vcc⁻. Therefore, the single supply comparator can be used as a dual supply comparator as well.

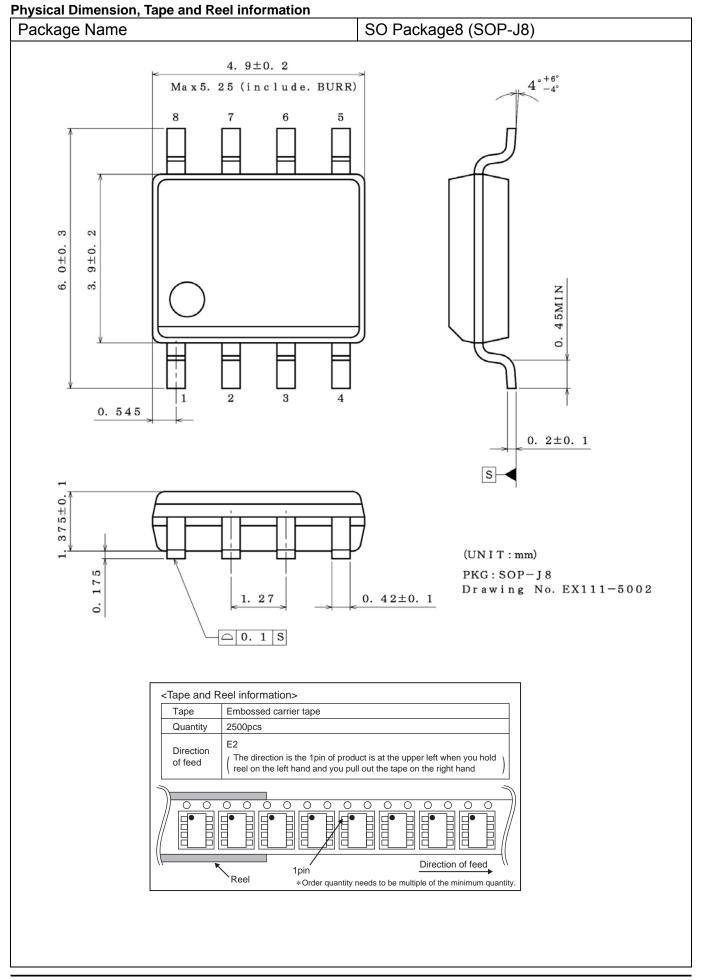
15. Terminal short-circuits

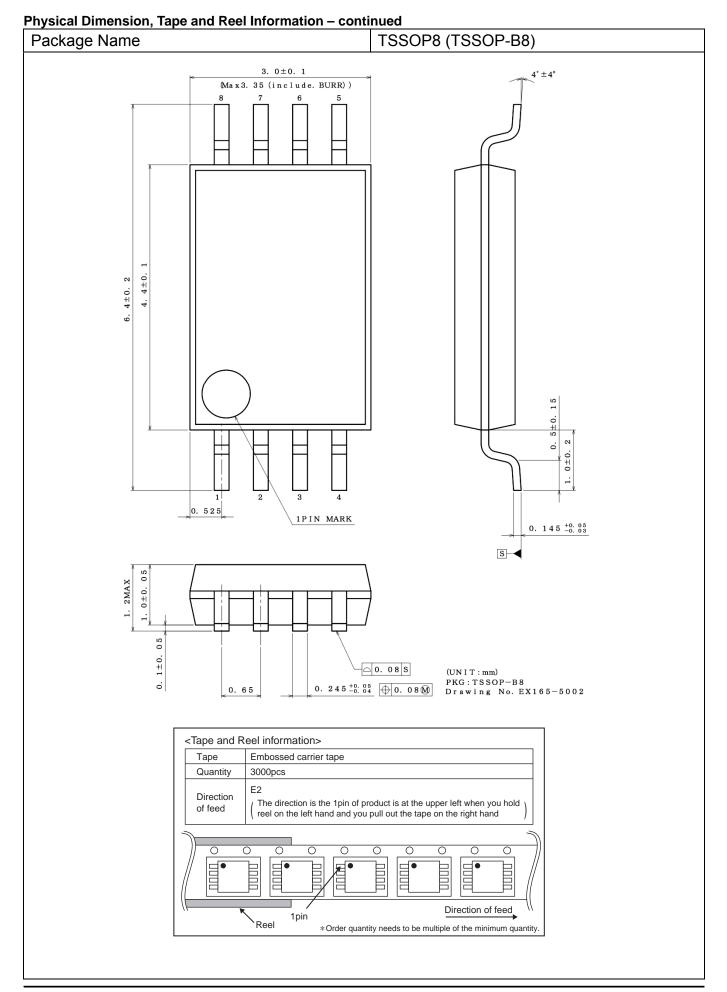
When the output and Vcc⁺ pins are shorted, excessive output current may flow, resulting in undue heat generation and, subsequently, destruction.

16. IC Handling

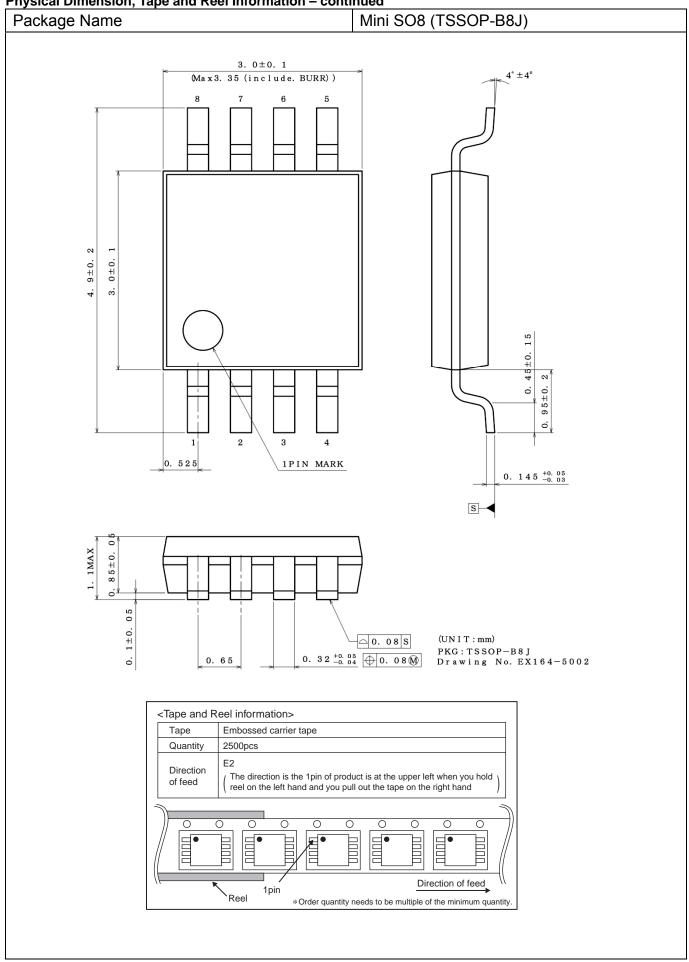
Applying mechanical stress to the IC by deflecting or bending the board may cause fluctuations in the electrical characteristics due to piezo resistance effects.

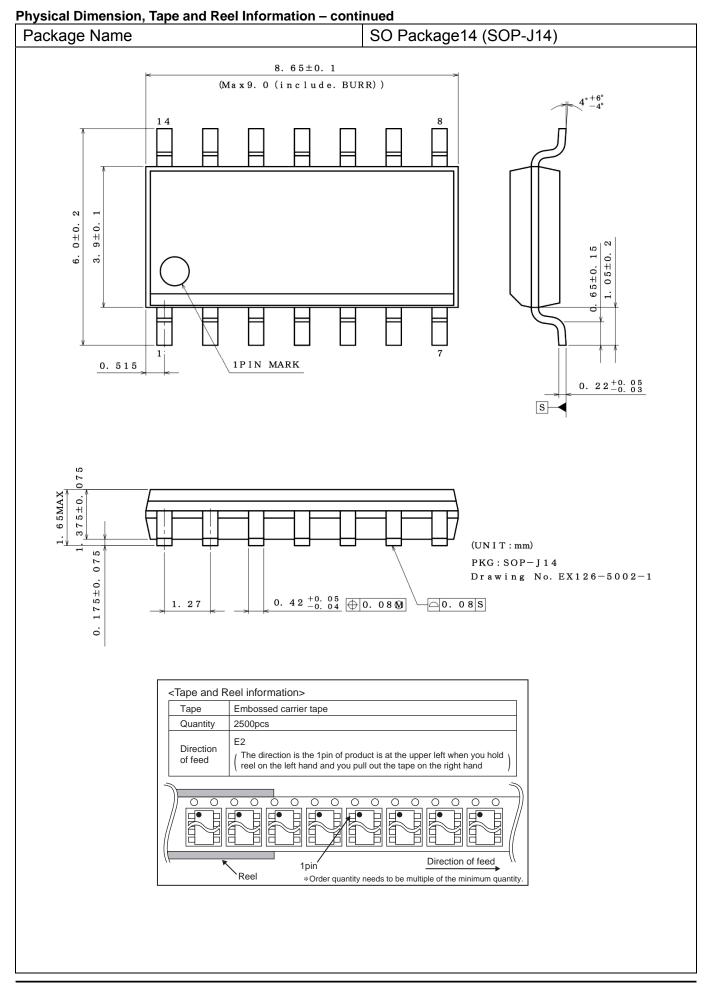
Datasheet











Physical Dimension, Tape and Reel Information - continued TSSOP14 (TSSOP-B14J) Package Name 5. 0 ± 0.1 (Max5. 35 (include. BURR)) $4^{\circ} \pm 4^{\circ}$ 148 -2 $4\pm0.$ $4\pm0.$.9 4. 2 5 ± 0.15 0 ± 0 . Ŀ. ö 1 1 0.55 1PIN MARK $0. \ 1\ 4\ 5\ {}^{+\ 0. \ 0\ 5}_{-\ 0. \ 0\ 3}$ S 02 1. 2MAX 0 ± 0 . 05 $\bigcirc 0.08S$ (UN I T : mm) $0. 1\pm 0.$ PKG:TSSOP-B14J 0. $245^{+0.05}_{-0.04} \oplus 0.08$ Ø 0.65 Drawing No. EX166-5002-1 <Tape and Reel information> Embossed carrier tape Таре 2500pcs Quantity F2 Direction The direction is the 1pin of product is at the upper left when you hold of feed reel on the left hand and you pull out the tape on the right hand Ο 0 \overline{O} Ō O C O E E E E É Direction of feed 1pin Reel *Order quantity needs to be multiple of the minimum quantity.

Ordering Information

L	М	х	Х	Х	Х	Х	Х	Т	
---	---	---	---	---	---	---	---	---	--

Part Number LM393DT LM393WDT LM393WDT LM393PT LM393WPT LM393ST LM339DT LM339DT LM393WPT	ESD Tolerance applicable W : 2kV None : Normal	Package type D : S.O package P : SSOP S : Mini SO	Packaging and forming specification T: Embossed tape and reel
LM2903DT LM2903PT			
LM2901DT LM2901PT			

Line-up

Topr	Channels	ESD	Packa	age	Orderable Part Number
	2	Normal	SO Package8	Reel of 2500	LM393DT
			TSSOP8	Reel of 2500	LM393PT
			Mini SO8	Reel of 2500	LM393ST
-40°C to +85°C		2kV	SO Package8	Reel of 2500	LM393WDT
			TSSOP8	Reel of 2500	LM393WPT
	4	Normal	SO Package14	Reel of 2500	LM339DT
			TSSOP14	Reel of 2500	LM339PT
	2	Normal	SO Package8	Reel of 2500	LM2903DT
-40°C to +125°C	2		TSSOP8	Reel of 2500	LM2903PT
-40 C to +125 C	4		SO Package14	Reel of 2500	LM2901DT
			TSSOP14	Reel of 2500	LM2901PT

Part Number Marking

LOT Number

Part Number Marking

LOT Number

1PIN MARK

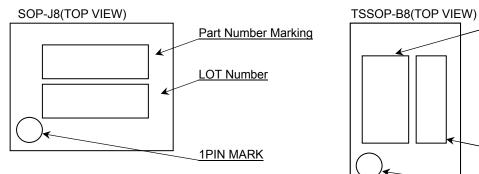
1PIN MARK

≰

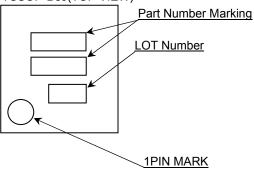
4

SOP-J14(TOP VIEW)

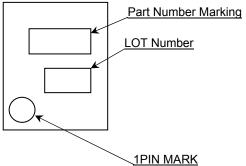
Marking Diagram



TSSOP-B8J(TOP VIEW)



TSSOP-B14J (TOP VIEW)

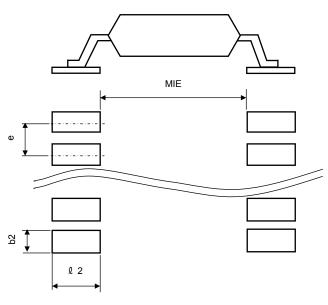


Product Name		Package Type	Marking	
	DT	SO Package8 (SOP-J8)		
	PT	TSSOP8 (TSSPO-B8)		
LM393	ST	Mini SO8 (TSSOP-B8J)	393	
	WDT	SO Package8 (SOP-J8)		
	WPT	TSSOP8 (TSSPO-B8)		
LM339	DT	SO Package14 (SOP-J14)	- 339	
	PT	TSSOP14 (TSSOP-B14J)	339	
LM2903	DT	SO Package8 (SOP-J8)	- 2903	
	PT	TSSOP8 (TSSPO-B8)	2903	
LM2901	DT	SO Package14 (SOP-J14)	- 2901	
	PT	TSSOP14 (TSSOP-B14J)	2901	

Land Pattern Data

			All d	imensions in mm
PKG	Land pitch e	Land space MIE	Land length ≥{ 2	Land width b2
SO Package8 (SOP-J8) SO Package14 (SOP-J14)	1.27	3.90	1.35	0.76
TSSOP8 (TSSPO-B8) TSSOP14 (TSSOP-B14J)	0.65	4.60	1.20	0.35
Mini SO8 (TSSOP-B8J)	0.65	3.20	1.15	0.35

SOP-J8, TSSOP-B8, TSSOP-B8J, SOP-J14, TSSOP-B14J



Revision History

Date	Revision	Changes
6.July.2015	001	New Release

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CLASSⅢ	CLASSⅢ	CLASS II b	
CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
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- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
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- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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LM2901DT - Web Page

Distribution Inventory

Part Number	LM2901DT
Package	SO package14
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes